



PCB1
DRV8837

Rev 0: Changed to USB Mini B connector to supply VCC and GND, removed extra hardware. Components placed on top & bottom layer to improve form factor.

Rev A: Added 0-ohm resistor in between LDO VCC output and EZ430 VCC connection. Changed POT to thumbwheel instead of trimmer. Changed PB switch to SPST

Rev B: Changed throughhole test points & switch to SMT, aesthetic changes made in PCB layout.

Title DRV8837 Customer EVM		
Factor Size A	Number	Revision B
Date:	6/15/2012	Sheet 1 of 1
File:	C:\Users\...\.DRV8837_38_51EVM2.SchDoc	Drawn By: Casey Leavitt

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